

ABSTRACT OF THE DISCLOSURE

A circuit board assembly has a circuit board and a column grid array ("CGA") integrated circuit package. The CGA integrated circuit package has a substrate having an array of solder columns extending from a bottom surface. An oversized lid is affixed to the substrate. Support shims are disposed between a portion of the lid that extends beyond an outer periphery of the substrate and a circuit board to which the CGA integrated circuit package is mounted. The support shims are affixed to the lid with adhesive after the CGA integrated circuit package is mounted on the circuit board. The adhesive accommodates any variations in height in the CGA integrated circuit package.

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